

PRODUCT/PROCESS CHANGE NOTICE (PCN)					
PCN Number: 22010 Date Issued: 3/17/2022 Product(s) Affected: PN MMID PEF7071VV16 947046 Manufacturing Location Affected: Greatek, Taiwan Date Effective (90 day window): Date Issued +90 days:	Means of Distinguishing Changed Devices: Product Mark: (Assembly Site Code) Back Mark Date Code Other				
Contact: Your local MaxLinear Marketing Representative or or contact our Customer Support team by creating a Support Ticket at http://www.maxlinear.com/support/createcase	Attachment: Yes No Samples: Request from MaxLinear				
Phone: 1-760-692-0711	Marketing Representatives				
Purpose of Change: To ensure continuity of supply MaxLinear will introduce a third source for its PEF7071VV16. The additional supplier will be Greatek Electronics Inc based in Taiwan. There is no change in form fit and function. The first deliveries from Greatek are planned for May, 2022. Description of Change: Introduction of Greatek as additional, fully qualified assembly provider fro the PEF707VV16. BOM Material change: Equivalent Performance: No change Software: No change External Hardware: No change Marking: No change Reliability: No change Documentation: No change, Datasheet and POD are the same	 □ Die Technology □ Wafer Fabrication □ Assembly Process □ Equipment ☑ Material □ Testing □ Product Desing ☑ Manufacturing Site □ Data Sheet □ Yield Enhancement □ Software ☑ Other: Second source Assembly Supplier 				
Reliability/Qualification Summary: N/A – same process as previously quali	fied				
Customer Acknowledgement of Receipt within 30 days of issue. Lack of acknowledger Please fax or email this form to the contact above after completing the following inform Customer: Name: Title: Date: E-Mail: Phone: Fax: Approval for shipments prior to effective date Customer Comments (Optional):					



Greatek Certifications

Greatek	ISO 9001	IATF16949	ISO 14001	ISO26262
Electronics Inc	Quality	Automotive Quality	Environmental Functional S	
	Management	Management System	Management System	Management
	System			

Comparison of Dimension & Materials (Prime Source/Second Source/Third Source)

	JCET	ASE KH	Greatek
MSL	3	3	3
Max soldering Temp [°C]	260	260	260
Dimensions LxWxH [mm]	7x7x0.9	7x7x0.9	7x7x0.9
Ball Pitch [mm]	0.4	0.4	0.4
Die Attach Glue	Ablebond 8290	EN-4900G	EN-4900GC
Mold Compound	EME-G770	EME-G631H	EME-G700H
Bond Wire	Cu-Pd, 0.8 mil	Cu-Pd, 0.8 mil	Cu-Pd, 0.8 mil
Lead Frame Base Material	C194	C194	C194
Inner Lead Frame Plating	Ag Double Ring	Ag Double Ring	Ag Double Ring
Outer Lead Frame Plating	Sn	Sn	Sn

Reliability Tests

Stress Test	Method	Test Condition	Duration	Sample Size	Result
uHAST	JESD22-A110-B	130°C/85% RH	96 h	3x25	0/75
Temp. Cycle	JESD22-A104-B	-55°C/+150°C	700x	3x25	0/75
High Temp. Storage	JESD22-A103-	150°C	1000h	3x25	0/75

Schedule

Samples available: Yes
Target date of First shipments: May 2022